PTO/S8/08a/b (08-03)
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Substitute for form 1449A/B/PTO				Complete If Known		
00044104	, 101 101111 1 1 1 1 1 1 1	J. 10		Application Number	Not Yet Assigned	
INFO	DRMATIC	ON DISC	CLOSURE	Filing Date	Concurrently Herewith	
STATEMENT BY APPLICANT			PLICANT	First Named Inventor	Masud Beroz	
		. •		Art Unit	3729	
	(Use as man	y sheets as ne	cessary)	Examiner Name	M. Trinh	
Sheet	1	of	2	Attorney Docket Number	TESSERA 3.0-205 A DIV	

			U.S. PA	TENT DOCUMENTS	
Examiner Initials	Cite No.1	Document Number Number-Kind Code ² (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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Examiner	Cite	Foreign Patent Document	Publication	Name of Patentee or	Pages, Columns, Lines,	
Initials*	No.	Country Code ³ -Number ⁴ -Kind Code ⁶ (if known)	Date MM-DD-YYYY	Applicant of Cited Document	Where Relevant Passages or Relevant Figures Appear	1
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Examiner Signature	Date Considered	7/05
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				Application Number	Not Yet Assigned	
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S	TATEMENT E	3Y /	APPLICANT	First Named Inventor	Masud Beroz	
				Art Unit	3729	
	(Use as many sh	eets as	necessary)	Examiner Name	M. Trinh	
Sheet	2	of	2	Attorney Docket Number	TESSERA 3.0-205 A DIV	

		NON PATENT LITERATURE DOCUMENTS	
Examiner Initials	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T²
T,	CA	Multi-Chip Module Technologies and Alternatives: The Basics (Doame and Franzon, eds., 1993, pp. 450-476).	
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[†]Applicant's unique citation designation number (optional). ²Applicant is to place a check mark here if English language Translation is attached.